TE Internal #: 50462-6

4.52 mm [.178 in] Socket Length, 1.32 mm [.052 in] PCB Hole,

Closed Bottom, .081 – .326 mm² Wire, 28 – 22 AWG, Cable-to-

Board, Pin Sockets

View on TE.com >



Connectors > Socket Connectors > Pin Sockets > Miniature Spring Sockets: Closed Bottom, Beryllium Copper, 4A











Socket Length: 4.52 mm [.178 in]

PCB Hole Diameter: 1.32 mm [.052 in]
Socket Sleeve Style: Closed Bottom

Wire Size: 28 – 22 AWG

All Miniature Spring Sockets: Closed Bottom, Beryllium Copper, 4A (13)

Features

Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Socket Sleeve Style	Closed Bottom
Connector System	Cable-to-Board
Sealable	No

Configuration Features

Compatible With Wire & Cable Type	Discrete Wire
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Body Features

Sleeve Plating Material	Gold Flash over Nickel
Sleeve Material	Copper

Contact Features

Contact Spring Plating Material	Gold
Contact Base Material	Beryllium Copper
Contact Mating Area Plating Material Thickness	30 μm[30 μin]
Contact Spring Plating Thickness	.76 µm[30 µin]



Contact Current Rating (Max)	4 A
Termination Features	
Termination Method to PCB	Through Hole - Press-Fit
Termination Method to Wire & Cable	Solder
Insertion Method	Hand/Semi-Automatic
Dimensions	
PCB Thickness (Recommended)	.79 – 3.18 mm[.031 – .125 in]
Socket Length	4.52 mm[.178 in]
PCB Hole Diameter	1.32 mm[.052 in]
Wire Size	28 – 22 AWG
Mating Pin Diameter Range	.36 – .66 mm[.014 – .026 in]
Usage Conditions	
Operating Temperature Range	-65 – 125 °C[-85 – 257 °F]
Operation/Application	
Circuit Application	Power & Signal
Packaging Features	
Packaging Method	Bag, Loose Piece
Packaging Quantity	2000
Other	
Spring Material	Beryllium Copper

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	有害物质含量符合标准要求 No Restricted Substance(s) Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2025 (250) Candidate List Declared Against: JUNE 2025 (250) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F < 900 ppm per homogenous material. Also BFR/CFR/PVC



Free

Solder Process Capability

Pin-in-Paste capable to 260°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Customers Also Bought













Documents

CAD Files

Customer View Model ENG_CVM_50462-6_AG1.3d_igs.zip

English

Customer View Model

ENG_CVM_50462-6_AG1.3d_stp.zip

English

Customer View Model

ENG_CVM_50462-6_AG1.2d_dxf.zip

English

4.52 mm [.178 in] Socket Length, 1.32 mm [.052 in] PCB Hole, Closed Bottom, .081 – . 326 mm² Wire, 28 – 22 AWG, Cable-to-Board, Pin Sockets



3D PDF

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Application Specification

English